

| Item | Technical Capability |
|---------------------------------|--|
| Layers: | 2--50layers |
| Max manufacturing size: | 650mm*1100mm |
| Copper foil thickness: | 0.5 oZ-20.0 oZ |
| Board thickness: | Double sided: 0.2mm-6.0mm |
| 4 layers: | 0.4mm-8.0mm |
| 6 layers: | 0.8mm-8.0mm |
| 8 layers: | 1.0mm-8.0mm |
| 10 layers: | 1.2mm-8.0mm |
| 12 layers: | 1.5mm-8.0mm |
| 14 layers: | 1.5mm-8.0mm |
| 16 layers: | 1.6mm-8.0mm |
| 18 layers: | 2.2mm-8.0mm |
| 20 layers: | 2.4mm-8.0mm |
| Min line width/space: | 3mil/3mil |
| Min finished holes size: | 0.15mm |
| Aspect ratio: | 12:01 |
| Impedance control: | +/-10% |
| Surface treatment: | HASL;LF HASL;ENIG;Immersion Silver;Immersion Tin;Gold Finger;Flash Gold;OSP |
| Materials: | FR4, Tg: 130°C/170°C,IT 180A,Bergquist,Rogers,Arlon,Taconic, PTFE. |
| Special technique: | blind & buried holes,via in pad,Semi-plating holes,countersink holes, Step mounting holes,controlled depth holes,Edge-plating PCB and metal base PCB. |

| Item | | Technical Parameters | Specification |
|--------------------------------------|-------------------------|--|---|
| Min.Line Width(mil) | | 3/4mil | Partial 3mil lines is allowed |
| Min.Space(mil) | | 3/4mil 4/5mil | Partial 4mil lines is allowed |
| Min. Annular Ring Width (mil) | | vias:3mil | Remained ring width means the distance between the hole edge to the ring outskirts. |
| | | Component Holes:6mils | |
| Min.Hole Size | Board Thickness<2.0mm | 0.15mm | — |
| | Board Thickness>=2.0mm | Aspect Ratio<=12 | — |
| Max.Board Thickness | Single and Double Sided | 6.0mm | |
| | Multilayer | 8.0mm | |
| Min.Board Thickness | Single and Double Sided | 0.15mm | |
| | Multilayer | 4 layers:0.4mm; 6 layers:0.6mm 8 layers:0.8mm;10 layers:1.0mm | |
| Max.Board Size | Single and Double Sided | 650*1100mm | |
| | Multilayer | 650*1100mm | |
| Distance between Line to Board edge | | Outline:0.20mm | |
| | | V-CUT:0.4mm | |
| Max.Layers | | 50 layers | |
| Solder mask | Mask Window(mil) | 2-4mil | 1. Single side; 2. 2mil is allowed for mask bridge or avoiding exposed lines. |
| | Mask Bridge(mil) | 6mil | Between IC pins |
| | Color | White,Black, Blue,Green, Yellow,Red,ect. | — |
| Legend | Min.Line Width(mil) | 5mil | — |
| | Color | White,Black, Yellow(orange),ect. | — |

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|---|--|---|----------------------|----------------------|---|
| Surface Plating | | HALS(with Pb free),ENIG,immersion silver,immersion tin,OSP, gold plating etc. | | | — |
| Plating Thickness(micro inch) | Technique | Plating Type | Min.Thickness | Max.Thickness | |
| | Plated Ni/Au | Ni | 100 | 150 | |
| | | Au | 1 | 3 | |
| | Immersion Ni/Au | Ni | 100 | 150 | |
| | | Au | 1 | 4 | |
| | Gold Finger | Ni | 120 | 150 | |
| | | Au | 5 | 20 | |
| Copper Plating Hole (micron) | | Copper Thickness | 20um | 30um | |
| Base Copper Thickness | Inner Layers and Outer Layers(OZ) | | 0.5 | 6 | |
| Finished Copper Thickness | Outer Layers | | 1 | 20 | Line width shouldn't be less than the required value under ensure of space. |
| | Inner Layers | | 0.5 | 6 | |
| Insulation Layer(mm) | | | 0.06mm | ---- | |
| 4/4; 4/5 | | | 0.5 OZ | — | |
| 4/6; 5/5; 6/5 | | | 1 OZ | — | |
| 5/6; 6/6 | | | 2 OZ | — | |
| 6/8; 7/8; 8/8 | | | 3 OZ | — | |
| 8/10; 9/10; 10/10 | | | 5 OZ | — | |
| Board Material | | FR-4; Aluminum Base; High Frequency; PFTE; FPC; Thick Copper; BT Base;PI Base; Tg130°C/ Tg170°C ,IT180A,Rogers,Berquist, Thermagon, (Taconic) | | | — |
| Finished Product Thickness Tolerance: | | | | | |
| T>=1.0mm, tolerance +/-0.1mm; 1.0mm<T<=1.6mm, tolerance +/-0.13mm; 1.6mm<T<2.0mm, tolerance +/-0.16mm; T>=2.0mm, tolerance +/-8% | | | | | |
| Tolerance of Impedance Control: | | | +/-10% | | |